The listing of claims will replace all prior versions, and listings, of claims in the present application:

LISTING OF CLAIMS:

Claim 1 (Currently Amended) A method for compensating threshold voltage rolloff within a semiconductor chip or system comprising the steps of:

designing a semiconductor chip or system having a plurality of transistor devices in which the channel length of each transistor device is equal to L_{nom} ;

setting off-current of each transistor device to I-off_{max} by predetermining that each transistor device has a channel length equal to L_{max} and then implanting into each channel of each transistor <u>device</u> such that <u>its</u> threshold voltage is equal to Vt_{min} ;

testing the off-current of each transistor device; and

biasing the back-gate back gate or the body nodes of some transistor devices, each of which has that have an off-current that does not meet a preselected specification of about I-off_{max}, to increase the threshold voltage of each of said transistor devices to about Vt_{min} thereof thereby compensating the threshold voltage roll-off within said semiconductor chip or system.

Claim 2 (Original) The method of Claim 1 wherein L_{nom} is 25 nm.

Claim 3 (Currently Amended) The method of Claim 1 wherein the <u>setting</u> offcurrent <u>setting</u> is controlled by varying implant conditions and ion dosage. Claim 4 (Currently Amended) The method of Claim 3 wherein the implanting is performed at an energy from about 5 keV to about 30 keV.

Claim 5 (Currently Amended) The method of Claim 3 wherein the ion dosage for a p-type dopant is from about 1E11 atoms/cm² to about 1E14 atoms/cm².

Claim 6 (Currently Amended) The method of Claim 3 wherein the ion dosage for an n-type dopant is from about 1E11 atoms/cm² to about 1E14 atoms/cm².

Claim 7 (Original) The method of Claim 3 wherein the implanting comprises a ptype dopant selected from ions of Group III elements.

Claim 8 (Original) The method of Claim 3 wherein the implanting comprises an n-type dopant selected from ions of Group V elements.

Claim 9 (Currently Amended) The method of Claim 1 wherein the biasing occurs after manufacturing of the semiconductor chip or system during the testing thereof.

Claim 10 (Currently Amended) The method of Claim 1 wherein the biasing occurs at a time after manufacturing of the semiconductor chip or system and after the testing thereof.

Claim 11 (Original) The method of Claim 1 wherein the biasing is achieved by an external DC voltage source.

Claim 12 (Currently Amended) The method of Claim 1 wherein the biasing is achieved by an internal circuit that can deliver a potential to the back gate back-gate or the body nodes of the second some transistor devices.

Claim 13 (Currently Amended) The method of Claim 1 wherein the biasing is achieved by an external clock system that can deliver a potential.